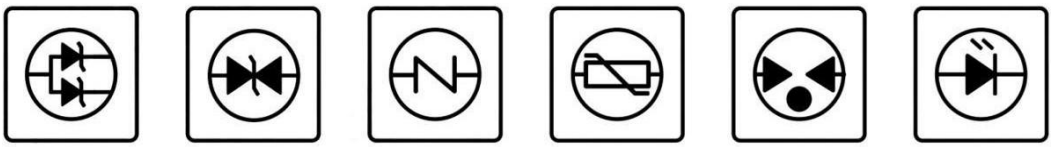
MSKSEMI 美森科
SEMICONDUCTOR



DSK22-MS THRU DSK210-MS

Product specification

DSK22-MS THRU DSK210-MS

FEATURES

- Ideal for surface mount applications
- Easy pick and place
- Built-in strain relief
- Low forward voltage drop

MECHANICAL DATA

- Case: Molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Metallurgically bonded construction
- Polarity: Color band denotes cathode end
- Mounting position: Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25℃ ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	DSK22-MS	DSK23-MS	DSK24-MS	DSK25-MS	DSK26-MS	DSK28-MS	DSK29-MS	DSK210-MS	UNITS
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	90	100	V
Maximum RMS Voltage	14	21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage	20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current See Fig. 1	2.0								A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	50								A
Maximum Instantaneous Forward Voltage at 2.0A	0.55			0.70		0.85			V
Maximum DC Reverse Current	0.1					0.02			mA
at Rated DC Blocking Voltage	5					2			mA
Typical Junction Capacitance (Note1)	170								pF
Typical Thermal Resistance $R_{\theta JA}$ (Note 2)	80								C/W
Operating Temperature Range T_J	-65 —— +150								℃
Storage Temperature Range T_{STG}	-65 —— +150								℃
Marking Code									

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Ambient.

RATING AND CHARACTERISTIC CURVES (DSK22 THRU DSK210)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

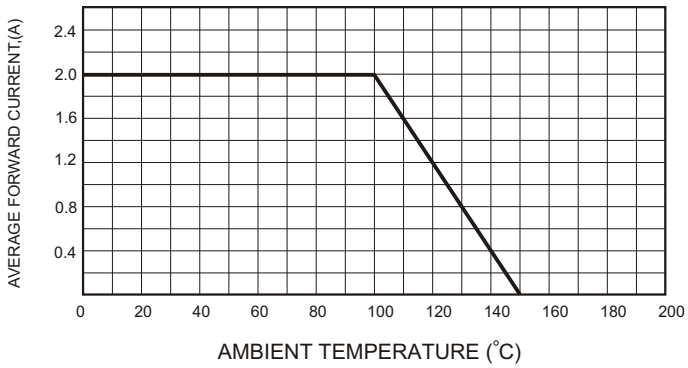


FIG.2-TYPICAL FORWARD CHARACTERISTICS

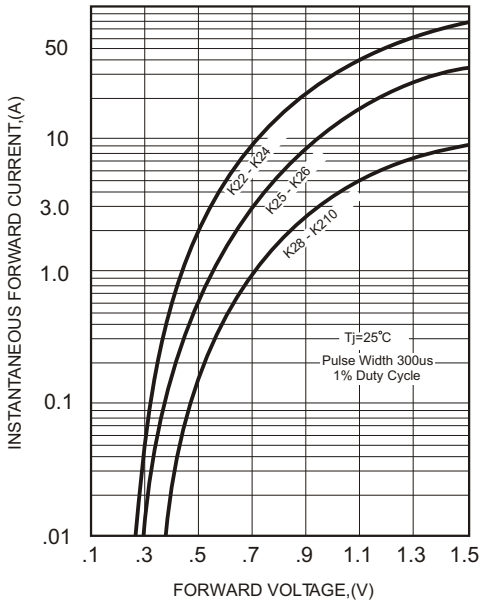


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

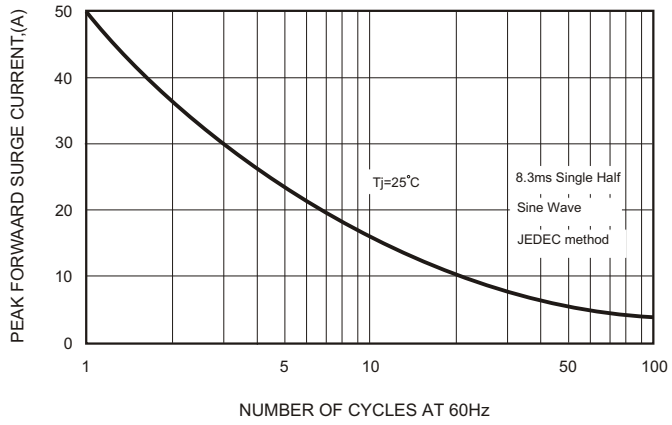


FIG.4-TYPICAL JUNCTION CAPACITANCE

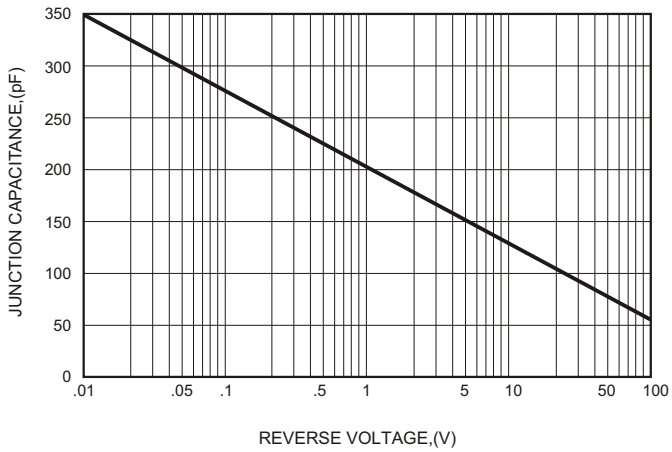
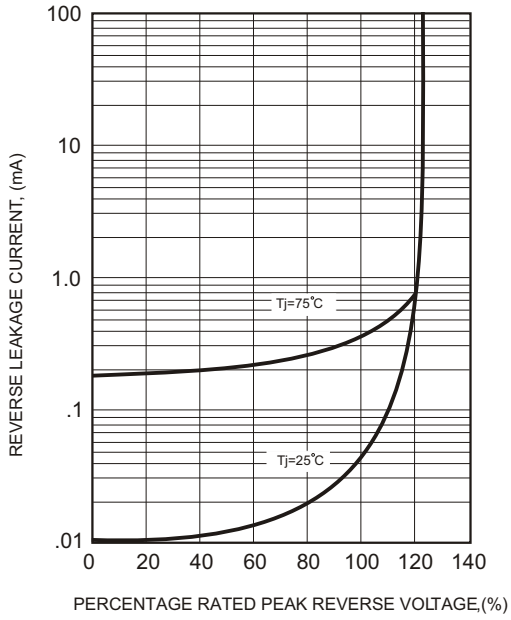
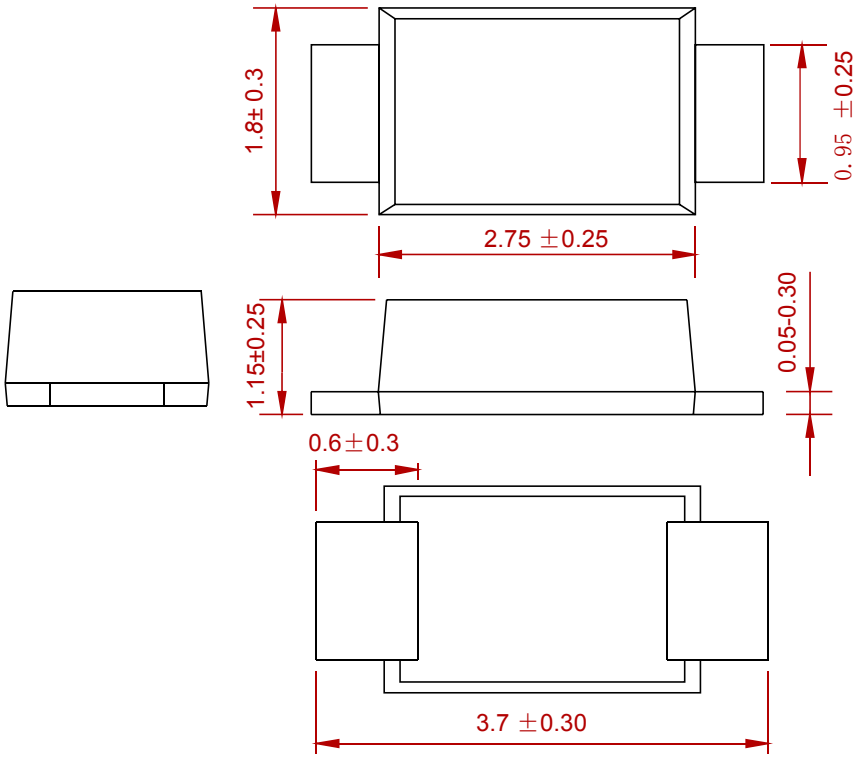


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

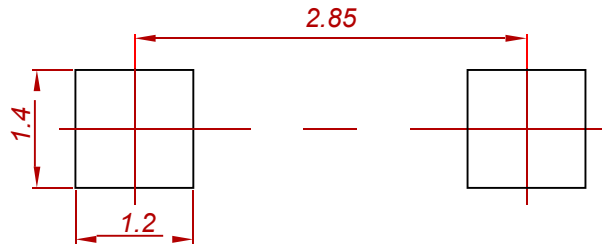


PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
DSK22-MS THRU DSK210-MS	SOD-123FL	3000

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